

What is claimed is:

1. A method of manufacturing an electronic device comprising: a mount substrate having a patterned conductor exposed on one of surfaces of the mount substrate; and an electronic component having a connection electrode formed on one of surfaces of the electronic component, the one of the surfaces of the electronic component that has the connection electrode formed thereon being disposed to face toward the one of the surfaces of the mount substrate, the connection electrode being electrically connected and mechanically bonded to the patterned conductor of the mount substrate, the method comprising the steps of:

disposing the electronic component and the mount substrate such that the one of the surfaces of the electronic component faces toward the one of the surfaces of the mount substrate, and electrically connecting and mechanically bonding the connection electrode of the electronic component to the patterned conductor of the mount substrate;

placing a resin film over the electronic component and the mount substrate;

deforming the resin film by sucking a gas existing on an electronic-component side of the mount substrate from the other side of the mount substrate through a hole provided in the mount substrate, such that the resin film covers the electronic component and the mount substrate in close contact with a surface of the electronic component that is farther from the mount substrate and with a part of the one of the surfaces of the mount substrate, the part being located around the electronic component; and

adhering the resin film to the mount substrate by heating the resin film to cause the resin film to fluidize and thereafter to harden.

2. A method of manufacturing an electronic device according to claim 1, wherein the resin film seals the electronic equipment.

3. A method of manufacturing an electronic device according to claim 1, wherein a cavity is formed between the one of the surfaces of the electronic component and the one of the surfaces of the mount substrate.

4. A method of manufacturing an electronic device according to claim 1, wherein the resin film is deformed with the resin film softened in the step of deforming the resin film.

5. A method of manufacturing an electronic device according to claim 1, wherein the hole formed in the mount substrate is disposed at a center portion of a region of the mount substrate where the electronic component is placed.

6. A method of manufacturing an electronic device according to claim 5, further comprising the step of closing the hole after the step of adhering the resin film.

7. A method of manufacturing an electronic device according to claim 1, wherein the hole formed in the mount substrate is disposed around a region of the mount substrate where the electronic component is placed, and the hole is closed with the resin film in the step of adhering the resin film.

8. A method of manufacturing an electronic device according to claim 1, wherein the hole formed in the mount substrate is a through hole for electrically connecting the patterned conductor disposed on the one of the surfaces of the mount substrate and another conductor provided in the mount substrate.

9. A method of manufacturing an electronic device according to claim 1, further comprising the step of predetermining a relationship between a processing condition employed in the step of adhering the resin film and a change in characteristics of the electronic component between before and after the step of adhering the resin film, wherein in the step of adhering the resin film, the processing condition is controlled based on said relationship so as to obtain desired characteristics of the electronic component.

10. A method of manufacturing an electronic device according to claim 9, wherein the processing condition includes at least one of a temperature of the resin film as heated and a period of time over which the resin film is heated.

11. A method of manufacturing an electronic device according to claim 9, wherein the resin film contains a hardening accelerator, and the processing condition includes a content of the hardening accelerator contained in the resin film.